

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A heating system comprising:  
a ceramic substrate having a mounting face for mounting a wafer having upper and lower faces~~an object~~, said ceramic substrate also having a back face and a side face;  
a heating means for generating heat from said mounting face of said ceramic substrate, said heating means comprising a heat generator embedded in said ceramic substrate; and  
a plate-shaped metal supporting member for supporting said back face of said ceramic substrate,  
wherein the entire lower face of the wafer opposes said mounting face of said ceramic substrate.

Claims 2-4 (Cancelled)

5. (Currently Amended) The system of claim 1, wherein said metal supporting member comprises a guide for positioning said wafer~~object~~.
6. (Original) The system of claim 1, wherein a space is formed between said ceramic substrate and said metal supporting member.
7. (Original) The system of claim 6, wherein one of said ceramic substrate and said metal supporting member comprises a protrusion for defining said space.

8. (Original) The system of claim 1, further comprising a tubular supporting member joined with said metal supporting member.
9. (New) A heating system comprising:
  - a ceramic substrate having a mounting face for mounting a wafer having upper and lower faces, said ceramic substrate also having a back face and a side face;
  - a heating means for generating heat from said mounting face of said ceramic substrate; and
  - a plate-shaped metal supporting member for supporting said back face of said ceramic substrate,wherein the entire lower face of the wafer opposes said mounting face of said ceramic substrate, and wherein said heating means is provided between said ceramic substrate and said metal supporting member.
10. (New) The system of claim 9, wherein said heating means comprises an insulator and a heat generator fixed onto said insulator.
11. (New) The system of claim 10, wherein said insulator is made of a material selected from the group consisting of mica and polyimide.
12. (New) The system of claim 9, wherein said metal supporting member comprises a guide for positioning said wafer.
13. (New) The system of claim 9, wherein a space is formed between said ceramic substrate and said metal supporting member.
14. (New) The system of claim 13, wherein one of said ceramic substrate and said metal supporting member comprises a protrusion for defining said space.

15. (New) The system of claim 9, further comprising a tubular supporting member joined with said metal supporting member.